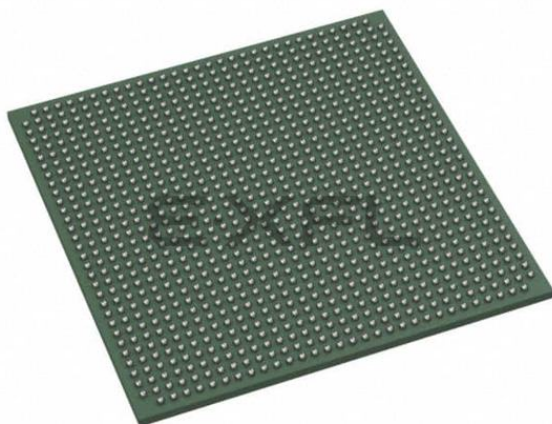




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Understanding **Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Obsolete
Number of LABs/CLBs	10000
Number of Logic Elements/Cells	40000
Total RAM Bits	4075520
Number of I/O	562
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1020-BBGA, FCBGA
Supplier Device Package	1020-OFCBGA (33x33)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga40ep1-5ffn1020c

Table 1-1. LatticeSC Family Selection Guide¹

Device	SC15	SC25	SC40	SC80	SC115
LUT4s (K)	15	25	40	80	115
sysMEM Blocks (18Kb)	56	104	216	308	424
Embedded Memory (Mbits)	1.03	1.92	3.98	5.68	7.8
Max. Distributed Memory (Mbits)	0.24	0.41	0.65	1.28	1.84
Number of 3.8Gbps SERDES (Max.)	8	16	16	32	32
DLLs	12	12	12	12	12
Analog PLLs	8	8	8	8	8
MACO Blocks	4	6	10	10	12
Package I/O/SERDES Combinations (1mm ball pitch)					
256-ball fpBGA (17 x 17mm)	139/4				
900-ball fpBGA (31 x 31mm)	300/8	378/8			
1020-ball fcBGA (33 x 33mm) ²		476/16	562/16		
1152-ball fcBGA (35 x 35mm) ³			604/16	660/16	660/16
1704-ball fcBGA (42.5 x 42.5mm) ³				904/32	942/32

1. The information in this preliminary data sheet is by definition not final and subject to change. Please consult the Lattice web site and your local Lattice sales office to ensure you have the latest information regarding the specifications for these products as you make critical design decisions.
2. Organic fcBGA converted to organic fcBGA revision 2 per [PCN #02A-10](#).
3. Ceramic fcBGA converted to organic fcBGA per [PCN #01A-10](#).

The LatticeSCM devices add MACO-enabled IP functionality to the base LatticeSC devices. Table 1-2 shows the type and number of each pre-engineered IP core.

Table 1-2. LatticeSCM Family

Device	SCM15	SCM25	SCM40	SCM80	SCM115
flexiMAC Blocks • 1GbE Mode • 10GbE Mode • PCI Express Mode	1	2	2	2	4
SPI4.2 Blocks	1	2	2	2	2
Memory Controller Blocks • DDR/DDR2 DRAM Mode • QDR II/II+ SRAM Mode • RLDRAM I • RLDRAM II CIO/SIO	1	2	2	2	2
Low-Speed CDR Blocks	0	0	2	2	2
PCI Express LTSSM (PHY) Blocks	1	0	2	2	2

Note: See each IP core user's guide for more information about support for specific LatticeSCM devices.

Introduction

The LatticeSC family of FPGAs combines a high-performance FPGA fabric, high-speed SERDES, high-performance I/Os and large embedded RAM in a single industry leading architecture. This FPGA family is fabricated in a state of the art technology to provide one of the highest performing FPGAs in the industry.

This family of devices includes features to meet the needs of today's communication network systems. These features include SERDES with embedded advance PCS (Physical Coding sub-layer), up to 7.8 Mbits of sysMEM embedded block RAM, dedicated logic to support system level standards such as RAPIDIO, SPI4.2, SFI-4, UTOPIA, XGMII and CSIX. The devices in this family feature clock multiply, divide and phase shift PLLs, numerous

Architecture Overview

The LatticeSC architecture contains an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM Embedded Block RAM (EBR). The upper left and upper right corners of the devices contain SERDES blocks and their associated PCS blocks, as shown in Figure 2-1.

Top left and top right corner of the device contain blocks of SERDES. Each block of SERDES contains four channels (quad). Each channel contains a single serializer and de-serializer, synchronization and word alignment logic. The SERDES quad connects with the Physical Coding Sub-layer (PCS) blocks that contain logic to simultaneously perform alignment, coding, de-coding and other functions. The SERDES quad block has separate supply, ground and reference voltage pins.

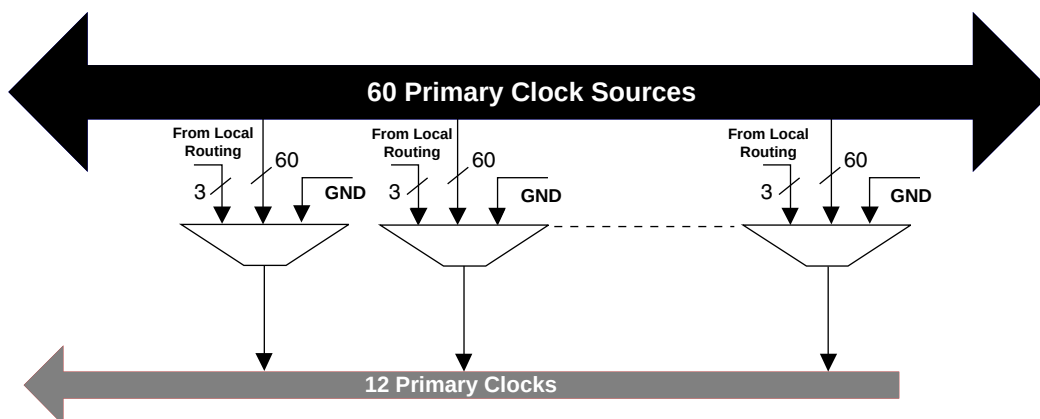
The PICs contain logic to facilitate the conditioning of signals to and from the I/O before they leave or enter the FPGA fabric. The block provides DDR and shift register capabilities that act as a gearbox between high speed I/O and the FPGA fabric. The blocks also contain programmable Adaptive Input Logic that adjusts the delay applied to signals as they enter the device to optimize setup and hold times and ensure robust performance.

sysMEM EBRs are large dedicated fast memory blocks. They can be configured as RAM, ROM or FIFO. These blocks have dedicated logic to simplify the implementation of FIFOs.

The PFU, PIC and EBR blocks are arranged in a two-dimensional grid with rows and columns as shown in Figure 2-1. These blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

The corners contain the sysCLOCK Analog Phase Locked Loop (PLL) and Delay Locked Loop (DLL) Blocks. The PLLs have multiply, divide and phase shifting capability; they are used to manage the phase relationship of the clocks. The LatticeSC architecture provides eight analog PLLs per device and 12 DLLs. The DLLs provide a simple delay capability and can also be used to calibrate other delays within the device.

Every device in the family has a JTAG Port with internal Logic Analyzer (ispTRACY) capability. The sysCONFIG™ port which allows for serial or parallel device configuration. The system bus simplifies the connections of the external microprocessor to the device for tasks such as SERDES and PCS configuration or interface to the general FPGA logic. The LatticeSC devices use 1.2V as their core voltage operation with 1.0V operation also possible.

Figure 2-6. Per Quadrant Clock Selection

Note: GND is available to switch off the network.

Secondary Clocks

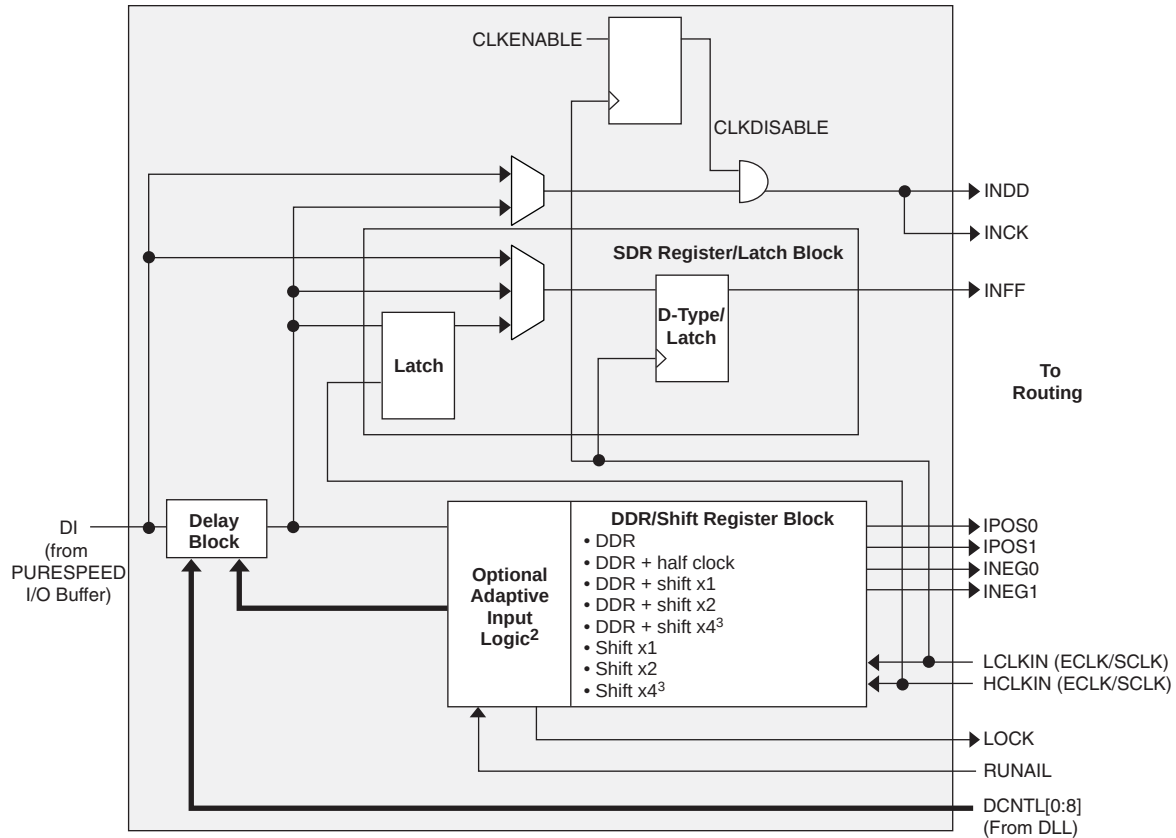
In addition to the primary clock network and edge clocks the LatticeSC devices also contain a secondary clock network. Built of X6 style routing elements this secondary clock network is ideal for routing slower speed clock and control signals throughout the device preserving high-speed clock networks for the most timing critical signals.

Edge Clocks

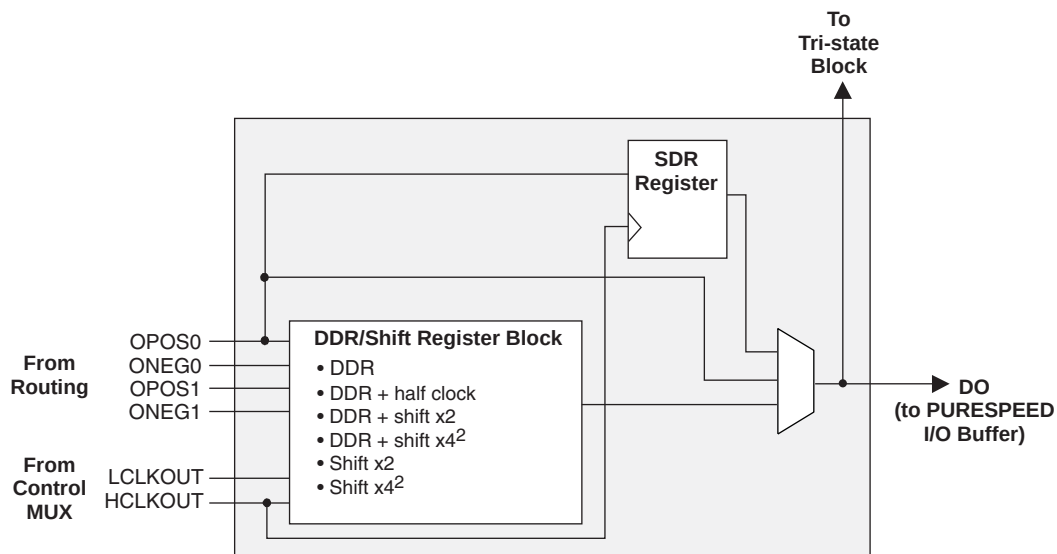
LatticeSC devices have a number of high-speed edge clocks that are intended for use with the PIOs in the implementation of high-speed interfaces. There are eight edge clocks per bank for the top and bottom of the device. The left and right sides have eight edge clocks per side for both banks located on that side. Figure 2-7 shows the arrangement of edge clocks.

Edge clock resources can be driven from a variety of sources. Edge clock resources can be driven from:

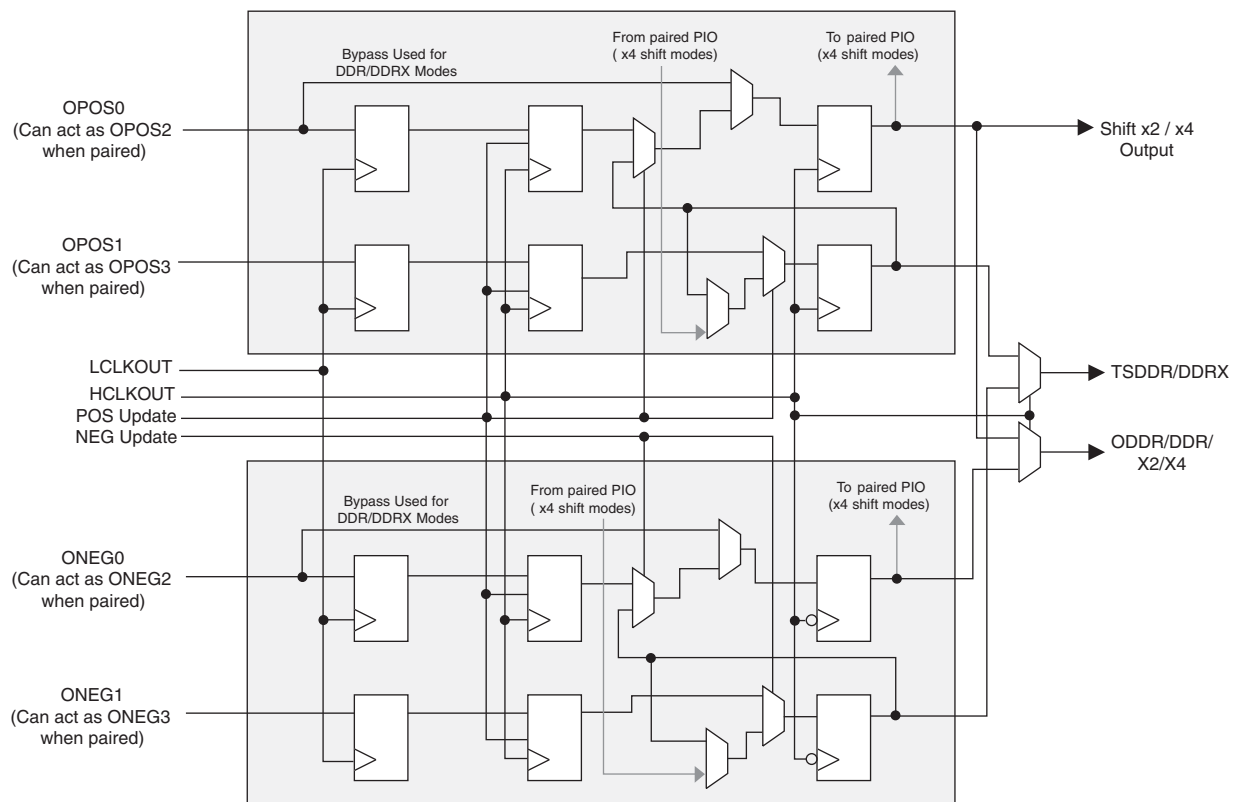
- Edge clock PIOs in the same bank
- Primary clock PIOs in the same bank
- Routing
- Adjacent PLLs and DLLs
- ELSR output from the clock divider

Figure 2-20. Input Register Block¹

1. UPDATE, Set and Reset not shown for clarity
2. Adaptive input logic is only available in selected PIO
3. By four shift modes utilize DDR/shift register block from paired PIO.
4. CLKDISABLE is used to block the transitions on the DQS pin during post-amble. Its main use is to disable DQS (typically found in DDR memory interfaces) or other clock signals. It can also be used to disable any/all input signals to save power.

Figure 2-22. Output Register Block¹**Notes:**

1. CE, Update, Set and Reset not shown for clarity.
2. By four shift modes utilizes DDR/Shift register block from paired PIO.
3. DDR/Shift register block shared with tristate block.

Figure 2-23. Output/Tristate DDR/Shift Register Block

PCI Specification, Revision 2.2 requires the use of clamping diodes for 3.3V operation. For more information on the PCI interface, please refer to the PCI Specification, Revision 2.2.

Programmable Slew Rate Control

All output and bidirectional buffers have an optional programmable output slew rate control that can be configured for either low noise or high-speed performance. Each I/O pin has an individual slew rate control. This allows designers to specify slew rate control on a pin-by-pin basis. This slew rate control affects both the rising and falling edges.

Programmable Termination

Many of the I/O standards supported by the LatticeSC devices require termination at the transmitter, receiver or both. The SC devices provide the capability to implement many kinds of termination on-chip, minimizing stub lengths and hence improving performance. Utilizing this feature also has the benefit of reducing the number of discrete components required on the circuit board. The termination schemes can be split into two categories single-ended and differential.

Single Ended Termination

Single Ended Outputs: The SC devices support a number of different terminations for single ended outputs:

- Series
- Parallel to V_{CCIO} or GND
- Parallel to $V_{CCIO}/2$
- Parallel to $V_{CCIO}/2$ combined with series

Figure 2-27 shows the single ended output schemes that are supported. The nominal values of the termination resistors are shown in Table 2-10.

PURESPEED I/O Single-Ended DC Electrical Characteristics

Over Recommended Operating Conditions

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL} (mA)	I_{OH} (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVC MOS 33	-0.3	0.8	2	3.465	0.4	2.4	24, 16, 8	-24, -16, -8
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVTTL	-0.3	0.8	2	3.465	0.4	2.4	24, 16, 8	-24, -16, -8
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVC MOS 25	-0.3	0.7	1.7	2.65	0.4	$V_{CCIO} - 0.4$	16, 12, 8, 4	-16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVC MOS 18	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	2.65	0.4	$V_{CCIO} - 0.4$	16, 12, 8, 4	-16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVC MOS 15	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	2.65	0.4	$V_{CCIO} - 0.4$	16, 12, 8, 4	-16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVC MOS 12	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	2.65	0.3	$V_{CCIO} - 0.3$	12, 8, 4, 2	-12, -8, -4, -2
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
PCIX15	-0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	1.5	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5
PCI33	-0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	3.465	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5
PCIX33	-0.3	$0.35V_{CCIO}$	$0.5V_{CCIO}$	3.465	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5
AGP-1X, AGP-2X	-0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	3.465	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5
SSTL3_I	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.465	0.7	$V_{CCIO} - 1.1$	8	-8
SSTS3_I OST ²	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.465	0.9	$V_{CCIO} - 1.3$	8	-8
SSTL3_II	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.465	0.5	$V_{CCIO} - 0.9$	16	-16
SSTL3_II OST ²	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.465	0.9	$V_{CCIO} - 0.13$	16	-16
SSTL2_I	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	2.65	0.54	$V_{CCIO} - 0.62$	7.6	-7.6
SSTL2_I OST ²	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	2.65	0.73	$V_{CCIO} - 0.81$	7.6	-7.6
SSTL2_II	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	2.65	0.35	$V_{CCIO} - 0.43$	15.2	-15.2
SSTL2_II OST ²	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	2.65	0.73	$V_{CCIO} - 0.81$	15.2	-15.2
SSTL18_I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	2.65	0.28	$V_{CCIO} - 0.28$	13.4	-13.4
SSTL18_II	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	2.65	0.28	$V_{CCIO} - 0.28$	13.4	-13.4
HSTL15_I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	2.65	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL15_II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	2.65	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL15_III ¹	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	2.65	N/A	N/A	N/A	N/A
HSTL15_IV ¹	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	2.65	N/A	N/A	N/A	N/A
HSTL18_I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	2.65	0.4	$V_{CCIO} - 0.4$	9.6	-9.6
HSTL18_II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	2.65	0.4	$V_{CCIO} - 0.4$	19.2	-19.2
HSTL18_III ¹	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	2.65	N/A	N/A	N/A	N/A
HSTL18_IV ¹	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	2.65	N/A	N/A	N/A	N/A
GTL12 ¹ , GTLPLUS15 ¹	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	N/A	N/A	N/A	N/A	N/A

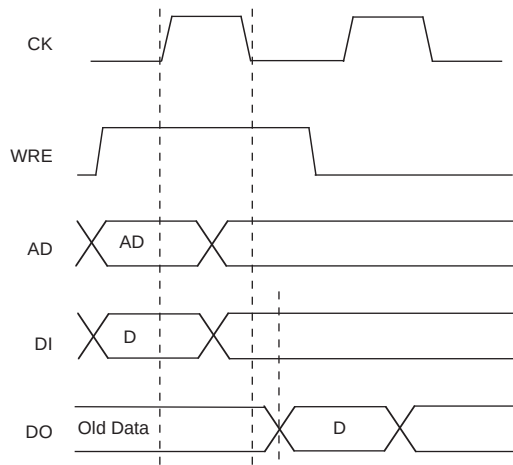
1. Input only.

2. Input with on-chip series termination.

Timing Diagrams

PFU Timing Diagrams

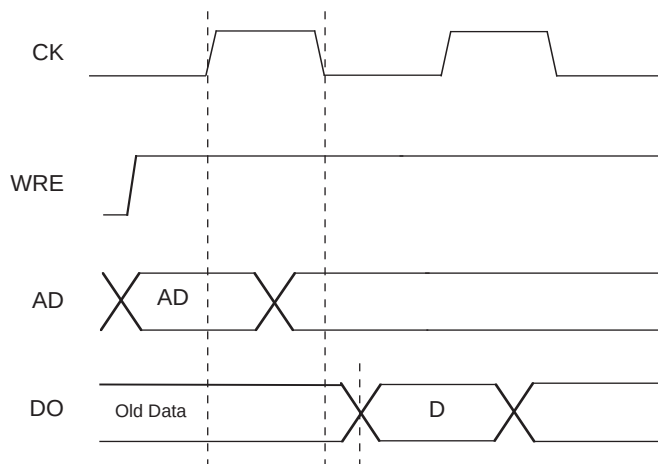
Figure 3-4. Slice Single/Dual Port Write Cycle Timing



Notes:

- Rising Edge for latching WREN, WAD and DATAIN.
- WREN must continue past falling edge clock.
- Data output occurs on negative edge.

Figure 3-5. Slice Single/Dual Port Read Cycle Timing



LatticeSC/M sysCONFIG Port Timing

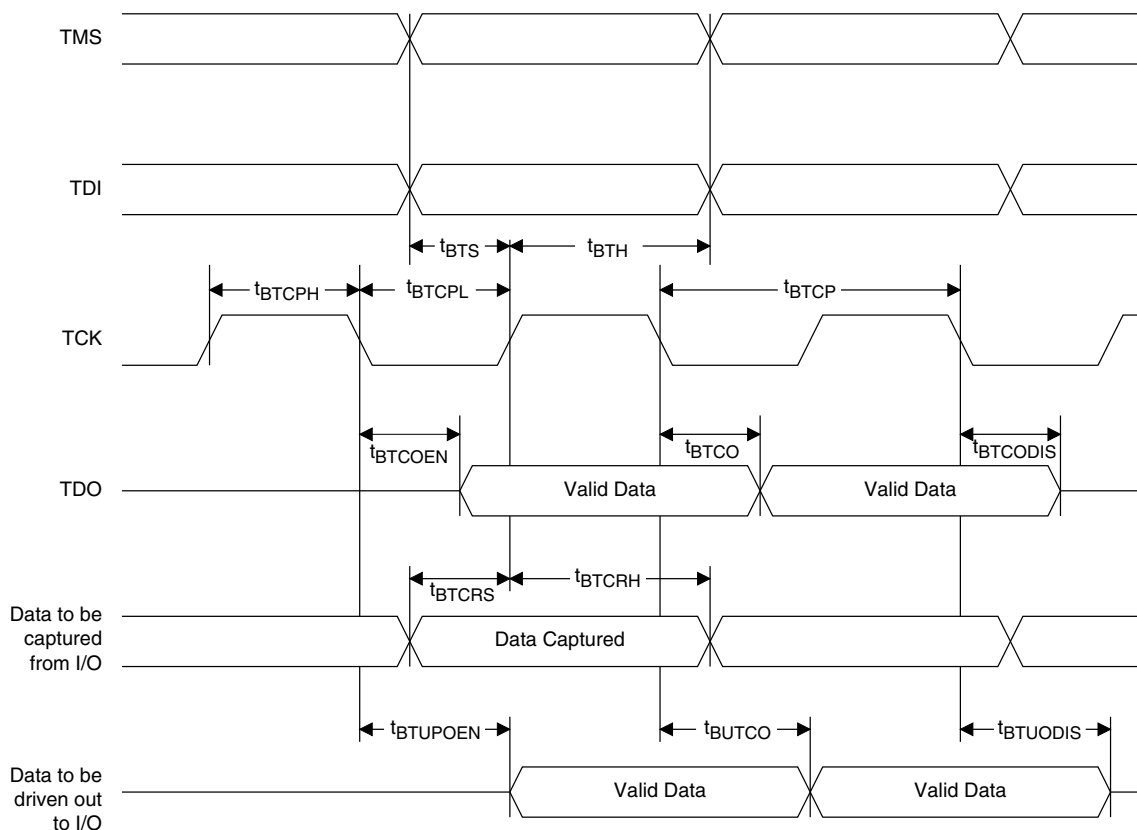
Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
General Configuration Timing				
t_{SMODE}	M[3:0] Setup Time to INITN High	0	—	ns
t_{HMODE}	M[3:0] Hold Time from INITN High	600	—	ns
t_{RW}	RESETN Pulse Width Low to Start Reconfiguration (1.2 V)	50 (or 100 at 0.95V)	—	ns
t_{PGW}	PROGRAMN Pulse Width Low to Start Reconfiguration (1.2 V)	50 (or 100 at 0.95V)	—	ns
$f_{ESB_CLK_FRQ}$	System Bus ESB_CLK Frequency (No Wait States)	—	133	MHz
sysCONFIG Master Parallel Configuration Mode				
t_{SMB}	D[7:0] Setup Time to RCLK High	6	—	ns
t_{HMB}	D[7:0] Hold Time to RCLK High	0	—	ns
t_{CLMB}	RCLK Low Time (Non-compressed Bitstreams)	0.5	0.5	CCLK periods
	RCLK Low Time (Compressed Bitstreams)	0.5	7.5	CCLK periods
t_{CHMB}	RCLK High Time	0.5	0.5	CCLK periods
sysCONFIG SPI Port				
t_{CFGX}	INITN High to CSCK Low	—	80	ns
t_{CSSPI}	INITN High to CSSPIN Low	0	2	μ s
t_{SCK}	CSCK Low before CSSPIN Low	0	—	ns
t_{SOCDO}	CSCK Low to Output Valid	—	15	ns
t_{CSPID}	CSSPIN Low to CSCK high Setup Time	—	15	ns
f_{MAXSPI}	Max CCLK Frequency - SPI Flash Fast Read Opcode (0x0B) (SPIFASTN=0)	—	50	MHz
t_{SUSPI}	SOSPI/D0 Data Setup Time Before CSCK	7	—	ns
t_{HSPI}	SOSPI/D0 Data Hold Time After CSCK	2	—	ns
	Master Clock Frequency	Selected value - 30%	Selected value + 30%	MHz
	Duty Cycle	40	60	%
sysCONFIG Master Serial Configuration Mode				
t_{SMS}	DIN Setup Time	4.4	—	ns
t_{HMS}	DIN Hold Time	0	—	ns
f_{CMS}	CCLK Frequency (No Divider)	90	190	MHz
f_{C_DIV}	CCLK Frequency (Div 128)	0.70	1.48	MHz
t_D	CCLK to DOUT Delay	—	7.5	ns
sysCONFIG Master Parallel Configuration Mode				
t_{AVMP}	RCLK to Address Valid	—	10	ns
t_{SMP}	D[7:0] Setup Time to RCLK High	6	—	ns
t_{HMP}	D[7:0] Hold Time to RCLK High	0	—	ns
t_{CLMP}	RCLK Low Time (Non-compressed Bitstream)	7.5	7.5	CCLK periods
	RCLK Low Time (Compressed Bitstream)	0.5	63.5	CCLK periods
t_{CHMP}	RCLK High Time	0.5	0.5	CCLK periods
t_{DMP}	CCLK to DOUT	—	7.5	ns

JTAG Port Timing Specifications

Over Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units
f_{MAX}		—	25	MHz
t_{BTCP}	TCK [BSCAN] Clock Pulse Width	40	—	ns
t_{BTCPH}	TCK [BSCAN] Clock Pulse Width High	20	—	ns
t_{BTCPL}	TCK [BSCAN] Clock Pulse Width Low	20	—	ns
t_{BTS}	TCK [BSCAN] Setup Time	8	—	ns
t_{BTH}	TCK [BSCAN] Hold Time	10	—	ns
t_{BTRF}	TCK [BSCAN] Rise/Fall Time	50	—	mV/ns
t_{BTCO}	TAP Controller Falling Edge of Clock to Valid Output	—	10	ns
t_{BTCODIS}	TAP Controller Falling Edge of Clock to Valid Disable	—	10	ns
t_{BTCOEN}	TAP Controller Falling Edge of Clock to Valid Enable	—	10	ns
t_{BTCRS}	BSCAN Test Capture Register Setup Time	8	—	ns
t_{BTCRH}	BSCAN Test Capture Register Hold Time	10	—	ns
t_{BUTCO}	BSCAN Test Update Register, Falling Edge of Clock to Valid Output	—	25	ns
t_{BTUODIS}	BSCAN Test Update Register, Falling Edge of Clock to Valid Disable	—	25	ns
t_{BTUPOEN}	BSCAN Test Update Register, Falling Edge of Clock to Valid Enable	—	25	ns

Figure 3-14. JTAG Port Timing Waveforms

LFSC/M15 Logic Signal Connections: 256 fpBGA^{1,2} (Cont.)

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
F14	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
E15	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
E14	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
D9	VCCJ	-	
C16	TDO	-	TDO
B15	TMS	-	
B16	TCK	-	
E13	TDI	-	
C14	PROGRAMN	1	
C15	CCLK	1	
A15	PT43D	1	HDC/SI
A14	PT43C	1	LDCN/SCS
B14	PT41A	1	CS1
E12	PT39B	1	CS0N
D13	PT39A	1	RDN
D12	PT37D	1	WRN
E10	PT37C	1	D7
C11	PT37B	1	D6
D10	PT37A	1	D5
A13	PT36D	1	D4
B12	PT36C	1	D3
A12	PT35B	1	D2
C12	PT35A	1	D1
A11	PT33B	1	D0
B11	PT33A	1	QOUT/CEON
E9	PT32D	1	VREF2_1
E8	PT32B	1	DOUT
D8	PT28C	1	BUSYN/RCLK/SCK
A10	PT27B	1	PCLKC1_0
C10	PT27A	1	PCLKT1_0
E7	PT21C	1	VREF1_1
C9	A_VDDIB3_L	-	
A9	A_HDINP3_L	-	PCS 360 CH 3 IN P
B9	A_HDINN3_L	-	PCS 360 CH 3 IN N
A8	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
B8	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
C8	A_VDDOB3_L	-	
B7	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
C7	A_VDDOB2_L	-	
A7	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
B6	A_HDINN2_L	-	PCS 360 CH 2 IN N
A6	A_HDINP2_L	-	PCS 360 CH 2 IN P
C6	A_VDDIB2_L	-	

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA^{1, 2} (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
R29	PR28B	3		PR31B	3	
P29	PR28A	3		PR31A	3	
P27	PR27C	3	PCLKT3_3	PR30C	3	PCLKT3_3
N29	PR27B	3		PR30B	3	
N28	PR27A	3		PR30A	3	
R25	PR26D	3	PCLKC3_1	PR29D	3	PCLKC3_1
R26	PR26C	3	PCLKT3_1	PR29C	3	PCLKT3_1
R28	PR26B	3	PCLKC3_0	PR29B	3	PCLKC3_0
P28	PR26A	3	PCLKT3_0	PR29A	3	PCLKT3_0
N27	PR24D	2	PCLKC2_2	PR27D	2	PCLKC2_2
P26	PR24C	2	PCLKT2_2	PR27C	2	PCLKT2_2
L30	PR24B	2	PCLKC2_0	PR27B	2	PCLKC2_0
K30	PR24A	2	PCLKT2_0	PR27A	2	PCLKT2_0
J30	PR23B	2	PCLKC2_1	PR26B	2	PCLKC2_1
H30	PR23A	2	PCLKT2_1	PR26A	2	PCLKT2_1
M26	PR22D	2	DIFFR_2	PR25D	2	DIFFR_2
M25	PR22C	2	VREF1_2	PR25C	2	VREF1_2
G29	PR22B	2		PR25B	2	
F29	PR22A	2		PR25A	2	
H28	PR19D	2		PR22D	2	
J28	PR19C	2		PR22C	2	
E30	PR19B	2		PR22B	2	
E29	PR19A	2		PR22A	2	
L26	PR18D	2	VREF2_2	PR18D	2	VREF2_2
L25	PR18C	2		PR18C	2	
F28	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
G28	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
K26	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
K25	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
D30	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
D29	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
G26	PR15D	2		PR16D	2	
H26	PR15C	2		PR16C	2	
E28	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
D28	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
J25	VCCJ	-		VCCJ	-	
H25	TDO	-	TDO	TDO	-	TDO
J26	TMS	-		TMS	-	
G25	TCK	-		TCK	-	
G24	TDI	-		TDI	-	
F26	PROGRAMN	1		PROGRAMN	1	
H24	MPIIRQN	1	CFGIRQN/MPI_IRQ_N	MPIIRQN	1	CFGIRQN/MPI_IRQ_N
F25	CCLK	1		CCLK	1	
D27	VCC12	-		VCC12	-	
E26	VCC12	-		VCC12	-	

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA^{1, 2} (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
Y9	VCCIO6	-		VCCIO6	-	
J7	VCCIO7	-		VCCIO7	-	
J8	VCCIO7	-		VCCIO7	-	
K7	VCCIO7	-		VCCIO7	-	
K8	VCCIO7	-		VCCIO7	-	
L8	VCCIO7	-		VCCIO7	-	
L9	VCCIO7	-		VCCIO7	-	
M9	VCCIO7	-		VCCIO7	-	
N9	VCCIO7	-		VCCIO7	-	
P9	VCCIO7	-		VCCIO7	-	
R9	VCCIO7	-		VCCIO7	-	
A1	GND	-		GND	-	
A30	GND	-		GND	-	
AA15	GND	-		GND	-	
AA16	GND	-		GND	-	
AK1	GND	-		GND	-	
AK30	GND	-		GND	-	
K15	GND	-		GND	-	
K16	GND	-		GND	-	
L11	GND	-		GND	-	
L12	GND	-		GND	-	
L13	GND	-		GND	-	
L14	GND	-		GND	-	
L15	GND	-		GND	-	
L16	GND	-		GND	-	
L17	GND	-		GND	-	
L18	GND	-		GND	-	
L19	GND	-		GND	-	
L20	GND	-		GND	-	
M11	GND	-		GND	-	
M12	GND	-		GND	-	
M13	GND	-		GND	-	
M14	GND	-		GND	-	
M15	GND	-		GND	-	
M16	GND	-		GND	-	
M17	GND	-		GND	-	
M18	GND	-		GND	-	
M19	GND	-		GND	-	
M20	GND	-		GND	-	
N11	GND	-		GND	-	
N12	GND	-		GND	-	
N13	GND	-		GND	-	
N14	GND	-		GND	-	
N15	GND	-		GND	-	
N16	GND	-		GND	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
H1	PR25B	2		PR23B	2	
H2	PR25A	2		PR23A	2	
N8	PR22D	2		PR25D	2	
M8	PR22C	2		PR25C	2	
H4	PR22B	2		PR25B	2	
J4	PR22A	2		PR25A	2	
G1	PR21B	2		PR22B	2	
G2	PR21A	2		PR22A	2	
L7	PR20D	2		PR21D	2	
L8	PR20C	2		PR21C	2	
F2	PR20B	2		PR21B	2	
F1	PR20A	2		PR21A	2	
K5	PR18D	2	VREF2_2	PR18D	2	VREF2_2
J5	PR18C	2		PR18C	2	
E2	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
E1	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
N10	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
M10	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
D2	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
D1	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
K6	PR16D	2		PR16D	2	
K7	PR16C	2		PR16C	2	
J8	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
K8	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
J10	VCCJ	-		VCCJ	-	
J9	TDO	-	TDO	TDO	-	TDO
K9	TMS	-		TMS	-	
J12	TCK	-		TCK	-	
J13	TDI	-		TDI	-	
K12	PROGRAMN	1		PROGRAMN	1	
K13	MPIIRQN	1	CFGIRQN/MPI_IRQ_N	MPIIRQN	1	CFGIRQN/MPI_IRQ_N
K10	CCLK	1		CCLK	1	
F5	RESP_URC	-		RESP_URC	-	
B5	VCC12	-		VCC12	-	
D5	A_REFCLKN_R	-		A_REFCLKN_R	-	
C5	A_REFCLKP_R	-		A_REFCLKP_R	-	
B2	A_VDDIB0_R	-		A_VDDIB0_R	-	
C1	A_HDINP0_R	-	PCS 3E0 CH 0 IN P	A_HDINP0_R	-	PCS 3E0 CH 0 IN P
C2	A_HDINN0_R	-	PCS 3E0 CH 0 IN N	A_HDINN0_R	-	PCS 3E0 CH 0 IN N
A3	A_HDOUPT0_R	-	PCS 3E0 CH 0 OUT P	A_HDOUPT0_R	-	PCS 3E0 CH 0 OUT P
D3	A_VDDOB0_R	-		A_VDDOB0_R	-	
B3	A_HDOUPTN0_R	-	PCS 3E0 CH 0 OUT N	A_HDOUPTN0_R	-	PCS 3E0 CH 0 OUT N
D4	A_VDDOB1_R	-		A_VDDOB1_R	-	
B4	A_HDOUPTN1_R	-	PCS 3E0 CH 1 OUT N	A_HDOUPTN1_R	-	PCS 3E0 CH 1 OUT N
A4	A_HDOUPT1_R	-	PCS 3E0 CH 1 OUT P	A_HDOUPT1_R	-	PCS 3E0 CH 1 OUT P
H5	A_HDINN1_R	-	PCS 3E0 CH 1 IN N	A_HDINN1_R	-	PCS 3E0 CH 1 IN N
G5	A_HDINP1_R	-	PCS 3E0 CH 1 IN P	A_HDINP1_R	-	PCS 3E0 CH 1 IN P
F4	A_VDDIB1_R	-		A_VDDIB1_R	-	
H6	A_VDDIB2_R	-		A_VDDIB2_R	-	
F6	A_HDINP2_R	-	PCS 3E0 CH 2 IN P	A_HDINP2_R	-	PCS 3E0 CH 2 IN P

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCI/O Bank	Dual Function	Ball Function	VCCI/O Bank	Dual Function
AH27	PB5C	5		PB5C	5	
AH26	PB5D	5	VREF1_5	PB5D	5	VREF1_5
AN32	PB7A	5		PB7A	5	
AP32	PB7B	5		PB7B	5	
AF25	PB7C	5		PB7C	5	
AE25	PB7D	5		PB7D	5	
AN31	PB8A	5		PB9A	5	
AN30	PB8B	5		PB9B	5	
AK29	PB8C	5		PB9C	5	
AK28	PB8D	5		PB9D	5	
AP31	PB9A	5		PB11A	5	
AP30	PB9B	5		PB11B	5	
AD24	PB9C	5		PB11C	5	
AE24	PB9D	5		PB11D	5	
AM29	PB11A	5		PB13A	5	
AM28	PB11B	5		PB13B	5	
AJ27	PB11C	5		PB13C	5	
AJ26	PB11D	5		PB13D	5	
AP29	PB13A	5		PB15A	5	
AP28	PB13B	5		PB15B	5	
AK27	PB13C	5		PB15C	5	
AK26	PB13D	5		PB15D	5	
AN29	PB15A	5		PB17A	5	
AN28	PB15B	5		PB17B	5	
AG25	PB15C	5		PB17C	5	
AG24	PB15D	5		PB17D	5	
AL26	PB17A	5		PB19A	5	
AL25	PB17B	5		PB19B	5	
AG23	PB17C	5		PB19C	5	
AG22	PB17D	5		PB19D	5	
AN27	PB19A	5		PB21A	5	
AN26	PB19B	5		PB21B	5	
AF24	PB19C	5		PB21C	5	
AF23	PB19D	5		PB21D	5	
AP27	PB22A	5		PB24A	5	
AP26	PB22B	5		PB24B	5	
AK25	PB22C	5		PB24C	5	
AK24	PB22D	5		PB24D	5	
AN25	PB25A	5		PB27A	5	
AN24	PB25B	5		PB27B	5	
AE22	PB25C	5		PB27C	5	
AE21	PB25D	5		PB27D	5	
AM26	PB26A	5		PB29A	5	
AM25	PB26B	5		PB29B	5	
AF22	PB26C	5		PB29C	5	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AB15	VCC12	-		VCC12	-	
AB20	VCC12	-		VCC12	-	
N15	VCC12	-		VCC12	-	
N20	VCC12	-		VCC12	-	
R13	VCC12	-		VCC12	-	
R22	VCC12	-		VCC12	-	
Y13	VCC12	-		VCC12	-	
Y22	VCC12	-		VCC12	-	
AA12	VCCAUX	-		VCCAUX	-	
AA23	VCCAUX	-		VCCAUX	-	
AB12	VCCAUX	-		VCCAUX	-	
AB16	VCCAUX	-		VCCAUX	-	
AB17	VCCAUX	-		VCCAUX	-	
AB18	VCCAUX	-		VCCAUX	-	
AB19	VCCAUX	-		VCCAUX	-	
AB23	VCCAUX	-		VCCAUX	-	
AC12	VCCAUX	-		VCCAUX	-	
AC13	VCCAUX	-		VCCAUX	-	
Y19	GND	-		GND	-	
AC14	VCCAUX	-		VCCAUX	-	
AC17	VCCAUX	-		VCCAUX	-	
AC21	VCCAUX	-		VCCAUX	-	
AC22	VCCAUX	-		VCCAUX	-	
AC23	VCCAUX	-		VCCAUX	-	
M13	VCCAUX	-		VCCAUX	-	
M14	VCCAUX	-		VCCAUX	-	
M18	VCCAUX	-		VCCAUX	-	
M21	VCCAUX	-		VCCAUX	-	
M22	VCCAUX	-		VCCAUX	-	
N12	VCCAUX	-		VCCAUX	-	
N16	VCCAUX	-		VCCAUX	-	
N17	VCCAUX	-		VCCAUX	-	
N18	VCCAUX	-		VCCAUX	-	
N19	VCCAUX	-		VCCAUX	-	
N23	VCCAUX	-		VCCAUX	-	
P12	VCCAUX	-		VCCAUX	-	
P23	VCCAUX	-		VCCAUX	-	
T13	VCCAUX	-		VCCAUX	-	
T22	VCCAUX	-		VCCAUX	-	
U12	VCCAUX	-		VCCAUX	-	
U13	VCCAUX	-		VCCAUX	-	
U22	VCCAUX	-		VCCAUX	-	
V13	VCCAUX	-		VCCAUX	-	
V22	VCCAUX	-		VCCAUX	-	
V23	VCCAUX	-		VCCAUX	-	

Industrial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA115E-6FCN1152I ¹	-6	Lead-Free Ceramic fcBGA	1152	IND	115.2
LFSC3GA115E-5FCN1152I ¹	-5	Lead-Free Ceramic fcBGA	1152	IND	115.2
LFSC3GA115E-6FFN1152I	-6	Lead-Free Organic fcBGA	1152	IND	115.2
LFSC3GA115E-5FFN1152I	-5	Lead-Free Organic fcBGA	1152	IND	115.2
LFSC3GA115E-6FCN1704I ¹	-6	Lead-Free Ceramic fcBGA	1704	IND	115.2
LFSC3GA115E-5FCN1704I ¹	-5	Lead-Free Ceramic fcBGA	1704	IND	115.2
LFSC3GA115E-6FFN1704I	-6	Lead-Free Organic fcBGA	1704	IND	115.2
LFSC3GA115E-5FFN1704I	-5	Lead-Free Organic fcBGA	1704	IND	115.2

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA115EP1-6FCN1152I ¹	-6	Lead-Free Ceramic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-5FCN1152I ¹	-5	Lead-Free Ceramic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-6FFN1152I	-6	Lead-Free Organic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-5FFN1152I	-5	Lead-Free Organic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-6FCN1704I ¹	-6	Lead-Free Ceramic fcBGA	1704	IND	115.2
LFSCM3GA115EP1-5FCN1704I ¹	-5	Lead-Free Ceramic fcBGA	1704	IND	115.2
LFSCM3GA115EP1-6FFN1704I	-6	Lead-Free Organic fcBGA	1704	IND	115.2
LFSCM3GA115EP1-5FFN1704I	-5	Lead-Free Organic fcBGA	1704	IND	115.2

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

